

Description

The AP15P06D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -60V I_{D} = -18.8A$

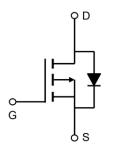
 $R_{DS(ON)} < 70 \text{m}\Omega$ @ $V_{GS}=10V$ (Type: $53 \text{m}\Omega$)

Application

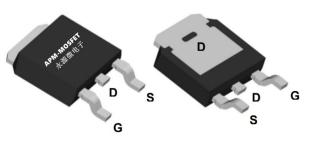
Brushless motor

Load switch

Uninterruptible power supply







Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP15P06D	TO-252-3	AP15P06D XXXX YYYY	2500

Absolute Maximum Ratings ((T _C =25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-60	V
Vgs	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-18.8	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-11	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-4.3	Α
ID@Ta=70°C	Continuous Drain Current, V _{GS} @ -10V ¹	-3.5	Α
Ірм	Pulsed Drain Current ²	-36	А
EAS	Single Pulse Avalanche Energy ³	35.4	mJ
las	Avalanche Current	-26.6	А
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-Ambient ¹	62	°C/W
Rejc	Thermal Resistance Junction-Case ¹	3.6	°C/W



Electrical Characteristics (T_A=25°Cunless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-60			V	
△BVDSS /△Tj	BV _{DSS} Temperature Coefficient	Reference to 25℃, I _D =-1mA		-0.03		V/°C	
DDC(ON)	Ctatia Dunin Cauras On Basistana	V _{GS} =-10V , I _D =-12A		53	70	mΩ	
RDS(ON)	Static Drain-Source On-Resistance	V _{GS} =-4.5V , I _D =-8A		64	105	mt2	
VGS(th)	Gate Threshold Voltage)/)/ L 050A	-1.2	-1.5	-2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, I_D =-250uA		4.56		mV/℃	
IDOO	Desire Course Losles as Course	V _{DS} =-48V , V _{GS} =0V , T _J =25℃			1		
IDSS	Drain-Source Leakage Current	V _{DS} =-48V , V _{GS} =0V , T _J =55℃			5	uA	
IGSS	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-12A		15.4		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		13.5		Ω	
Qg	Total Gate Charge (-4.5V)			9.86			
Qgs	Gate-Source Charge V _{DS} =-48V , V _{GS} =-4.5V , I _D =-			3.08		nC	
Q_{gd}	Gate-Drain Charge			2.95			
Td(on)	Turn-On Delay Time			28.8			
Tr	Rise Time	V _{DD} =-15V , V _{GS} =-10V , R _G =3.3□,		19.8		no	
Td(off)	Turn-Off Delay Time	I _D =-1A		60.8		ns	
T _f	Fall Time			7.2			
Ciss	Input Capacitance			1447			
Coss	Output Capacitance	apacitance V _{DS} =-15V , V _{GS} =0V , f=1MHz		97.3		pF	
Crss	Reverse Transfer Capacitance			70			
Is	Continuous Source Current ^{1,5}	\/ -\/ -0\/ Faras O:			-18	Α	
ISM	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			-36	Α	
VSD	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V	

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width $\leq 300 \text{us}$, duty cycle $\leq 2\%$
- 3. The EAS data shows Max. rating . The test condition is VDD=-25V,VGS=-10V,L=0.1mH,IAS=-26.6A
- 4. The power dissipation is limited by 150 $\!\!\!^{\circ}\!\!\!^{\circ}$ junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

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Typical Characteristics

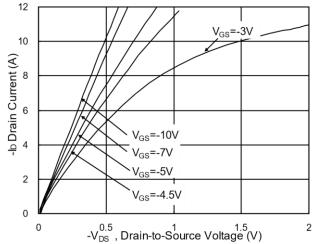


Fig.1 Typical Output Characteristics

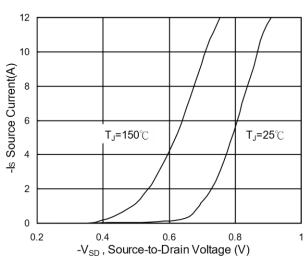


Fig.3 Forward Characteristics of Reverse

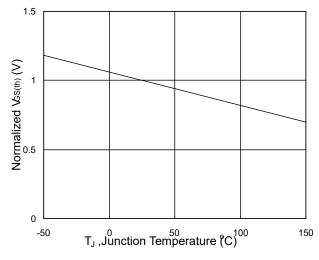


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

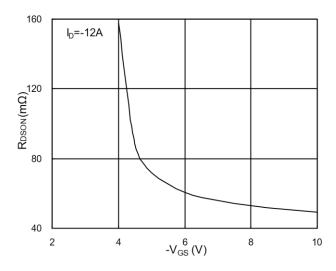


Fig.2 On-Resistance v.s Gate-Source

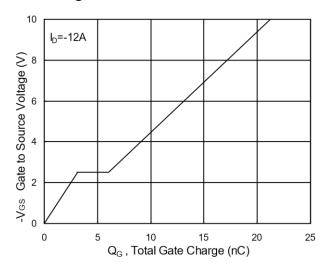


Fig.4 Gate-Charge Characteristics

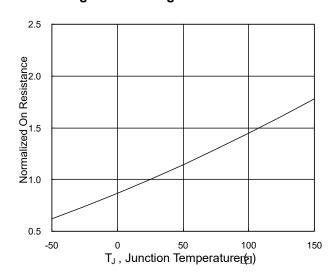
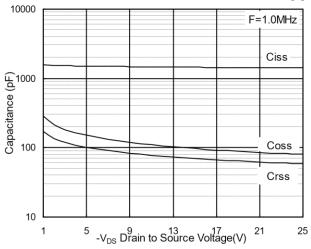


Fig.6 Normalized R_{DSON} v.s T_J







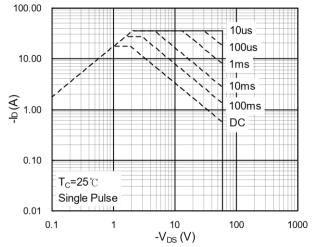


Fig.7 Capacitance

Fig.8 Safe Operating Area

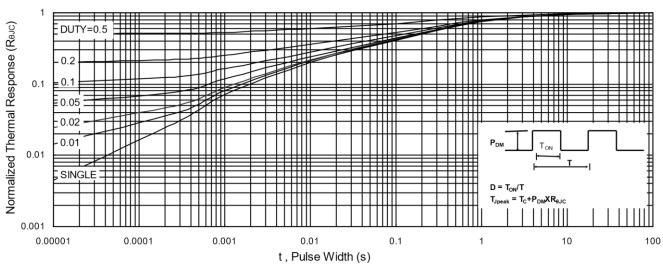


Fig.9 Normalized Maximum Transient Thermal Impedance

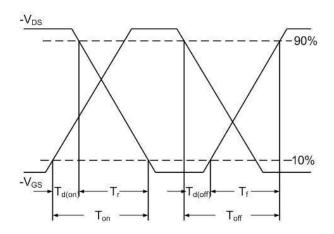


Fig.10 Switching Time Waveform

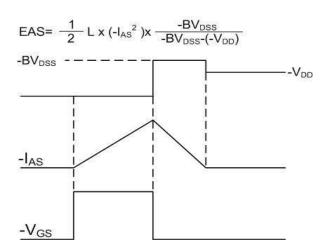
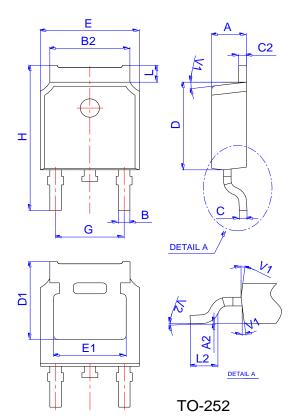


Fig.11 Unclamped Inductive Waveform

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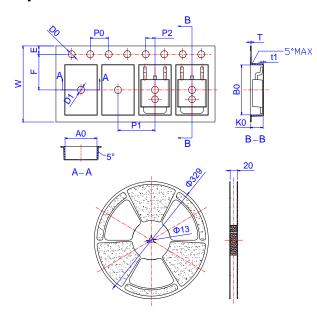


Package Mechanical Data



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
Е	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Spectification-TO-252



	Dimensions					
Ref.	Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
Е	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
Т	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583





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Edition	Date	Change
Rve3.8	2018/1/31	Initial release
Rve3.9	2018/5/25	Reduce CiSS and QG
Rve4.0	2021/4/13	Change layout format

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